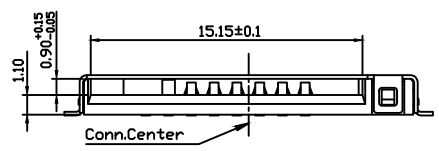


RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

▨ SOLDER AREA

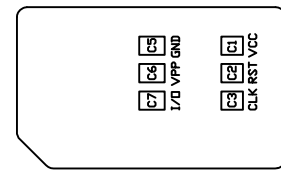
PIN NO.	Description
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/D
P7#	CD SW LOWER
P8#	CD SW UPPER



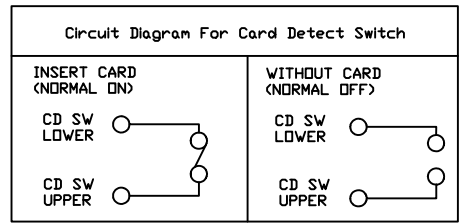
Material:
Housing:HI-Temp Plastic,UL94V-0,Rated
Contact:Copper Alloy
Shell:Stainless Steel,SUS 301, T=0.20mm

Plating:
Contact Area:G/F Plated Over 30u" Nickel
Solder Area:80u" Tin Plated Over 30u" Nickel
Under Plate:30u" Min Nickel.
Shell:30u" Min,Nickel Plated Over All,Solder
Area:Gold Flash

Electrical:
Current Rating:0.5 A
Dielectric Withstanding Voltage:250V AC/DC
Insulation Resistance:500MΩ Min.
Contact Resistance:100mΩ Max
Mating Cycles:5000 Insertions.
Operating Temperature:-40°C TO+85°C



SIM Diagram
Chip Face Down



NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4	SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5
			CHK'D BY FENG
			APPR BY ZHAN

Micro SIM CONN:PUSH/PUSH,
6Pin,H2.2mm,SMD With CD Pin
THIRD ANGLE PROJECTION
RHTAYIM-030A-6P-H2.2-R